

TM12H04DF

N+N-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

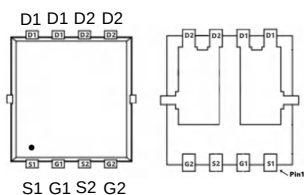
General Features

$V_{DS} = 40V$ $I_D = 12A$

$R_{DS(ON)} = 28m\Omega(Typ.) @ V_{GS}=10V$

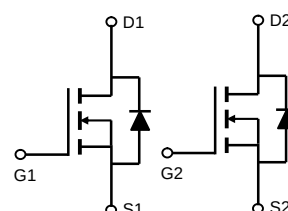
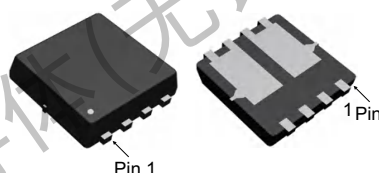
100% UIS Tested

100% R_g Tested



Marking:12H04

DF:DFN3x3-8L



Absolute Maximum Ratings ($T_C=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V$	12	A
$I_D @ T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V$	8.4	A
I_{DM}	Pulsed Drain Current	48	A
EAS	Single Pulse Avalanche Energy	5.5	mJ
I_{AS}	Avalanche Current	---	A
$P_D @ T_C=25^{\circ}C$	Total Power Dissipation	14	W
T_{STG}	Storage Temperature Range	-55 to 175	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 175	$^{\circ}C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	---	---	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	8.9	$^{\circ}C/W$

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Sourctce Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	40	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =40V	---	---	1	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0A	---	---	±100	nA
On Characteristics						
V _{GS(th)}	Gate-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	1.2	1.6	2.0	V
R _{DS(ON)}	Drain-Source On Resistance	V _{GS} =10V, I _D =10A	---	28	35	m Ω
		V _{GS} =4.5V, I _D =5A	---	36	47	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =20V, V _{GS} =0V, f=1MHz	---	530	---	pF
C _{oss}	Output Capacitance		---	44	--	
C _{rss}	Reverse Transfer Capacitance		---	34	---	
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DS} =20V, I _D =3A, R _G =3 Ω, V _{GS} =10V	---	4.6	---	ns
t _r	Rise Time		---	2	---	ns
t _{d(off)}	Turn-Off Delay Time		---	47	---	ns
t _f	Fall Time		---	372	---	ns
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =20V, I _D =3A	---	11	---	nC
Q _{gs}	Gate-Source Charge		---	2.2	---	nC
Q _{gd}	Gate-Drain “Miller” Charge		---	2	---	nC
Drain-Source Diode Characteristics						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _{SD} =30A	---	---	1.2	V
I _S	Continuous Drain Curren	V _D =V _G =0V	---	---	12	A
I _{SM}	Pulsed Drain Current		---	---	48	A
T _{rr}	Reverse Recovery Time	I _F =3A, T _J =25℃	---	8.5	---	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/us	---	3.8	---	nC

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Typical Characteristics: ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

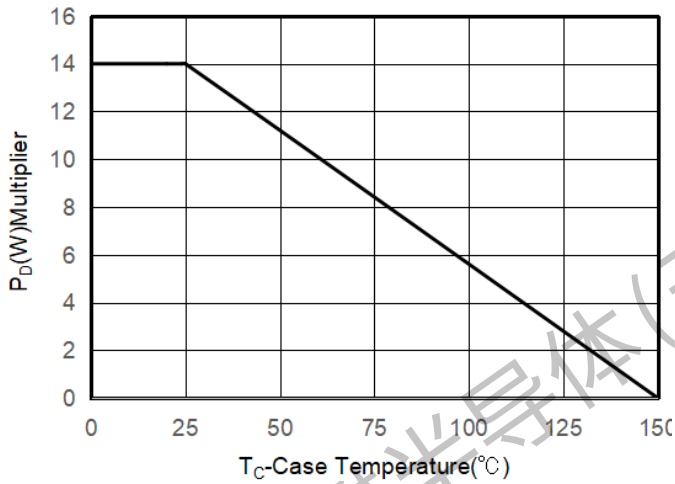


Figure 1: Power De-rating

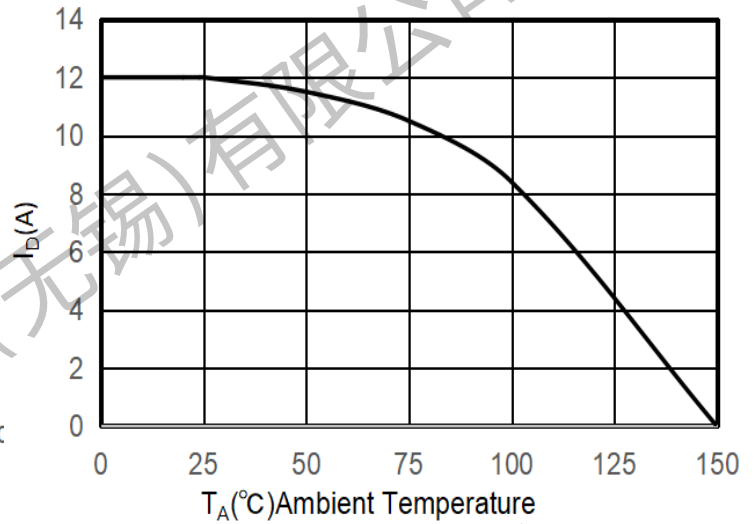


Figure 2: Current De-rating

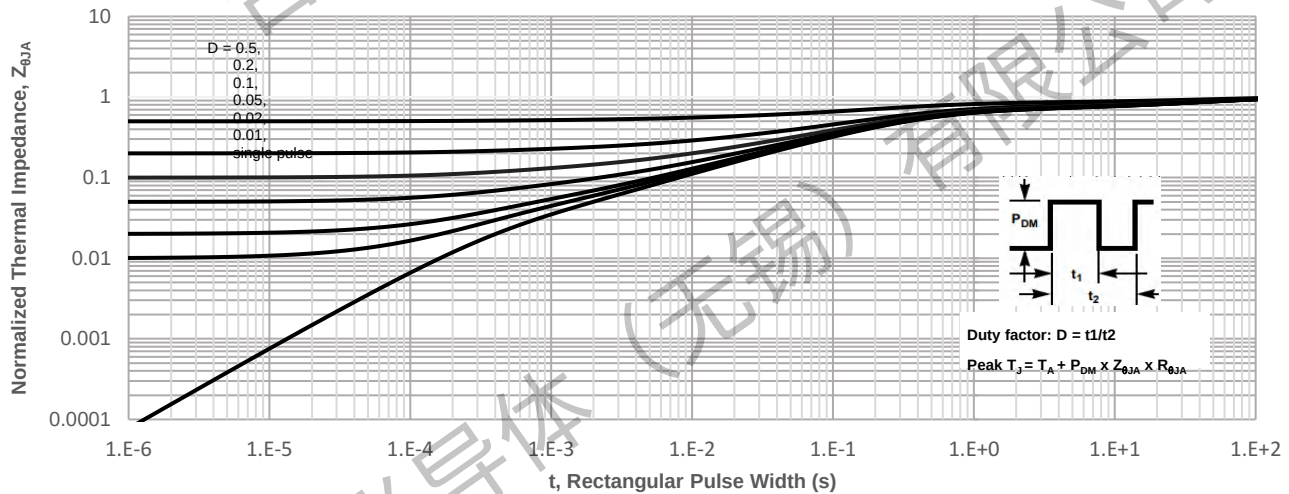


Figure 3: Normalized Maximum Transient Thermal Impedance

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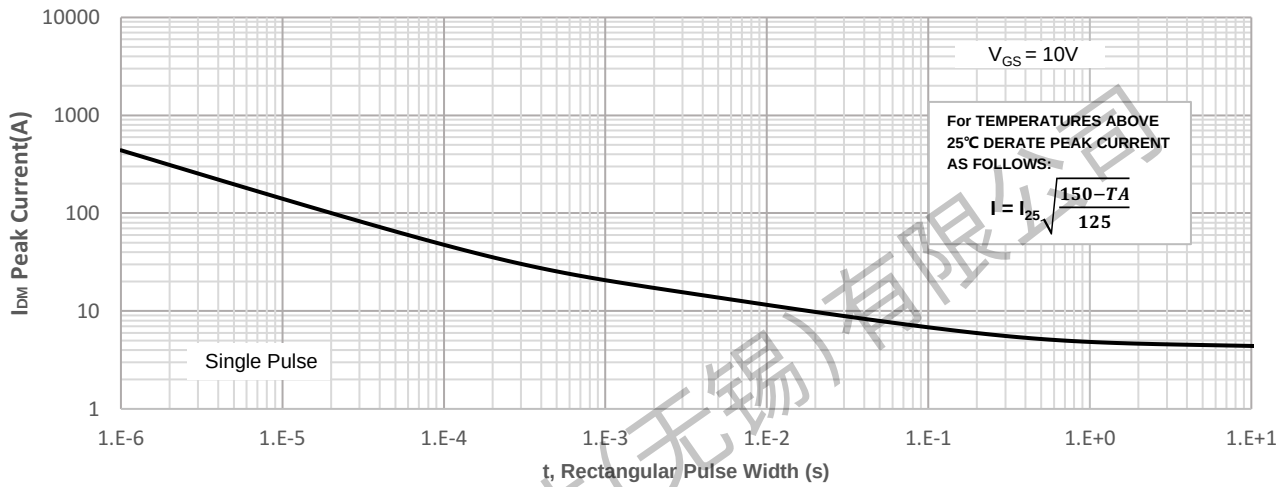


Figure 4: Peak Current Capacity

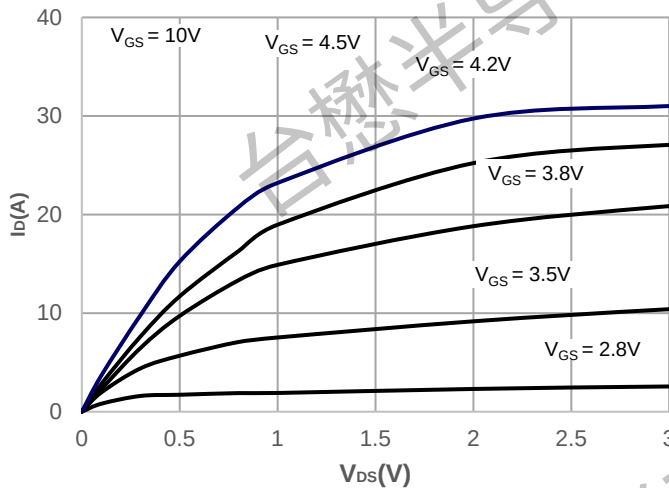


Figure 5: Output Characteristics

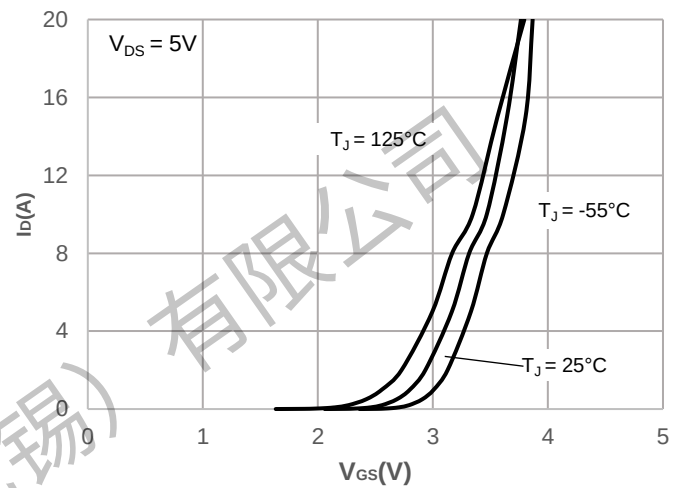


Figure 6: Typical Transfer Characteristics

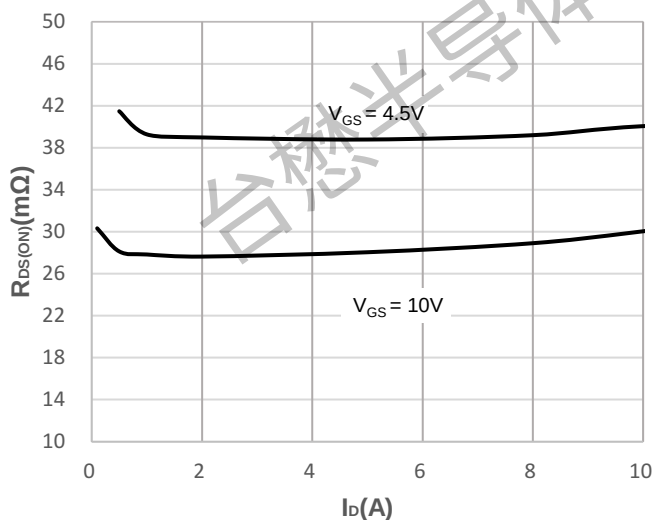


Figure 7: On-resistance vs. Drain Current

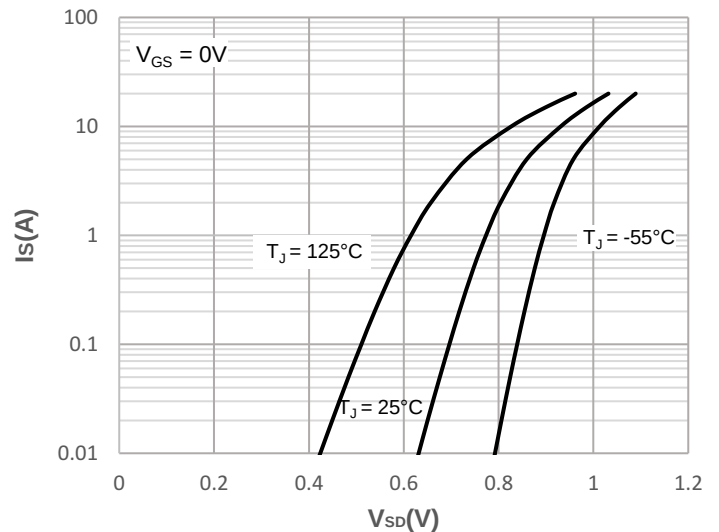
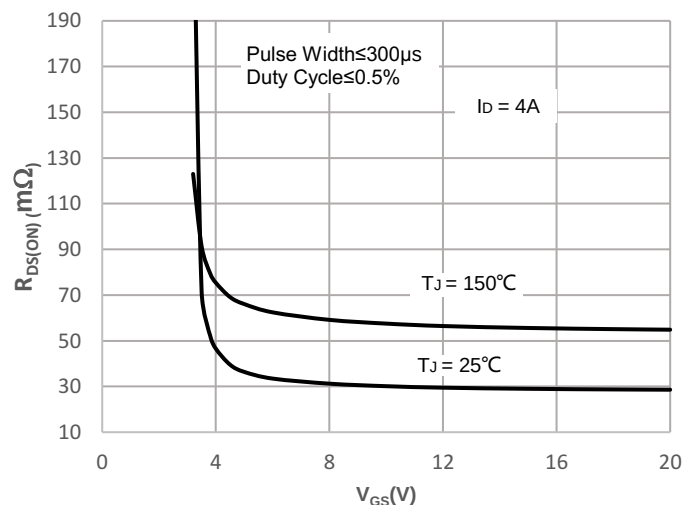
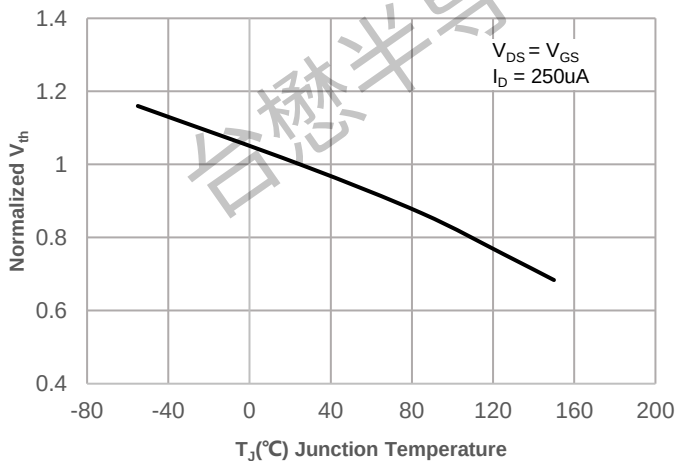
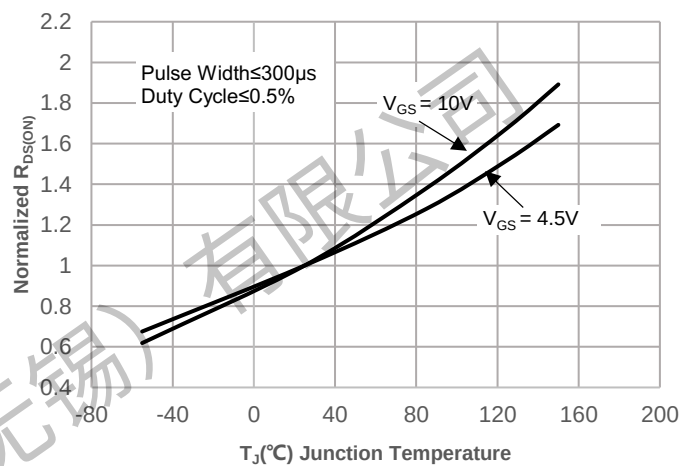
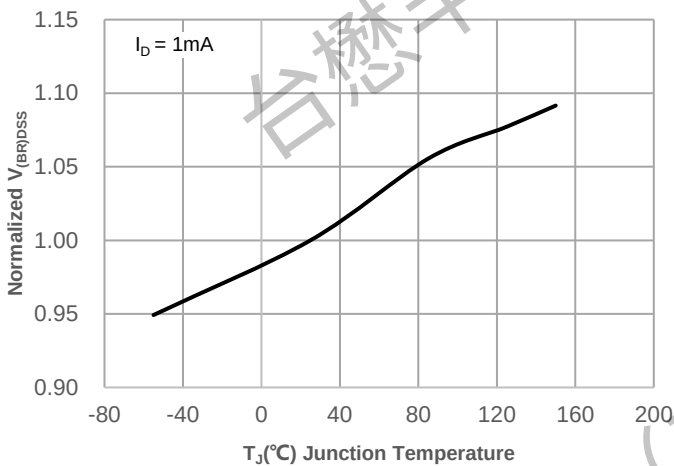
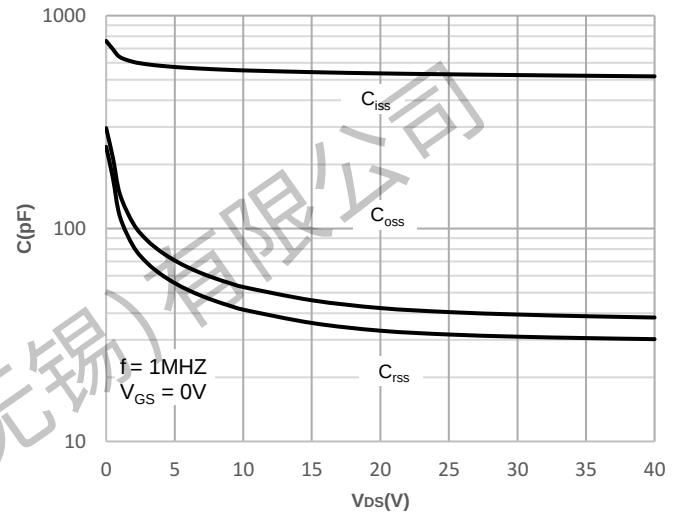
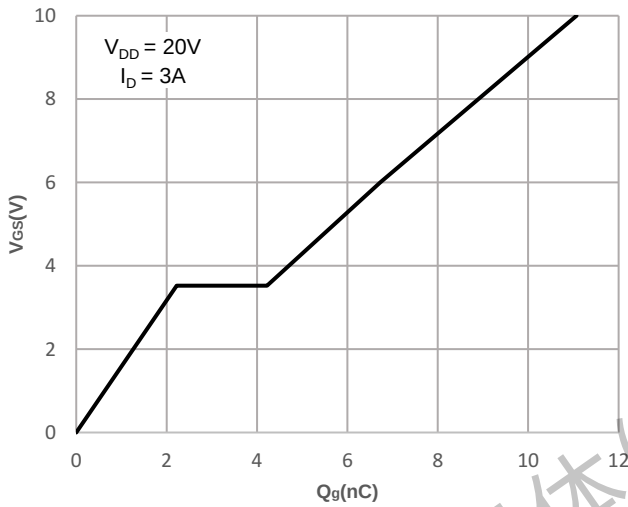


Figure 8: Body Diode Characteristics



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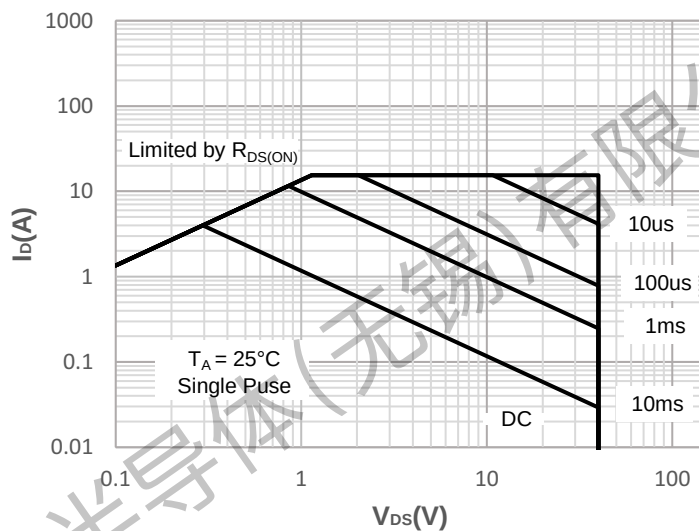
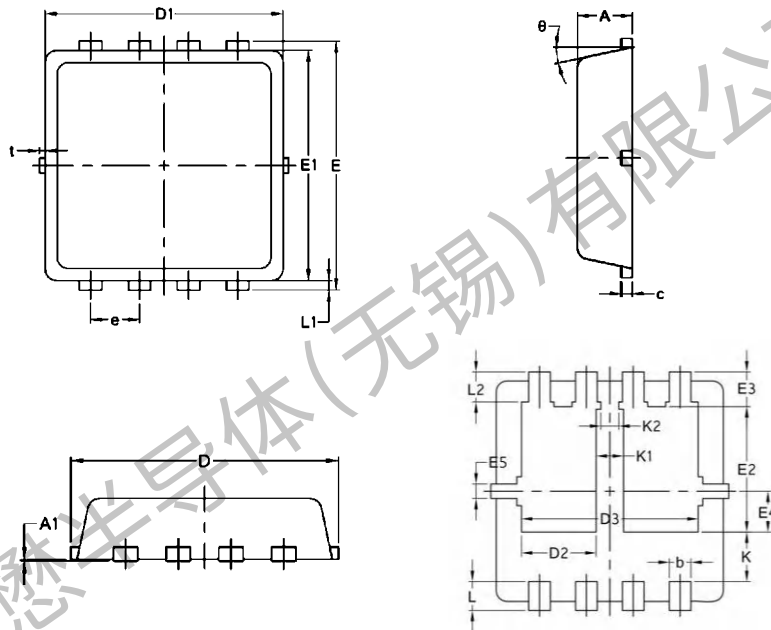


Figure 15: Maximum Safe Operating Area

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Package Mechanical Data:DFN3x3-8L

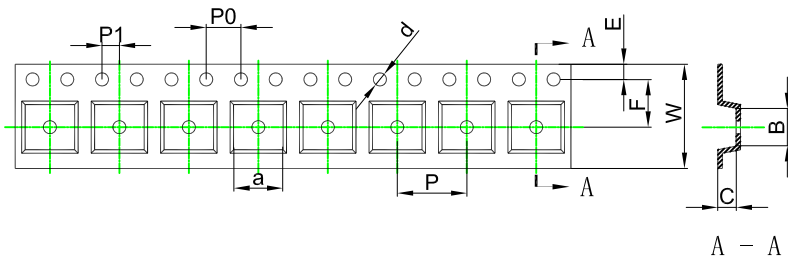


Symbol	Common		
	Min	Mm Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.25	0.30	0.39
c	0.14	0.152	0.20
D	3.20	3.30	3.45
D1	3.05	3.15	3.25
D2	0.84	1.04	1.24
D3	2.30	2.45	2.60
E	3.20	3.30	3.40
E1	2.95	3.05	3.15
E2	1.60	1.74	1.90
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.50	0.69	0.80
K1	0.30	0.38	0.53
K2	0.15	0.25	0.35
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
L2	0.27	0.42	0.57
t	0	0.075	0.13
Φ	10°	12°	14°

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PDFN3×3-8L Embossed Carrier Tape



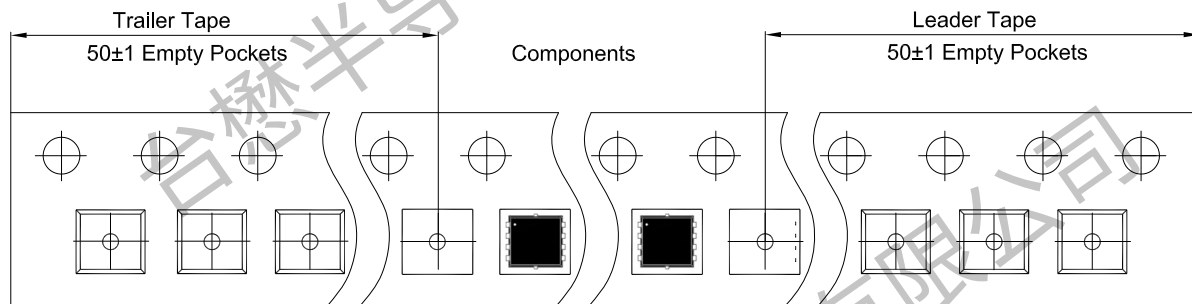
Packaging Description:

SOP-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

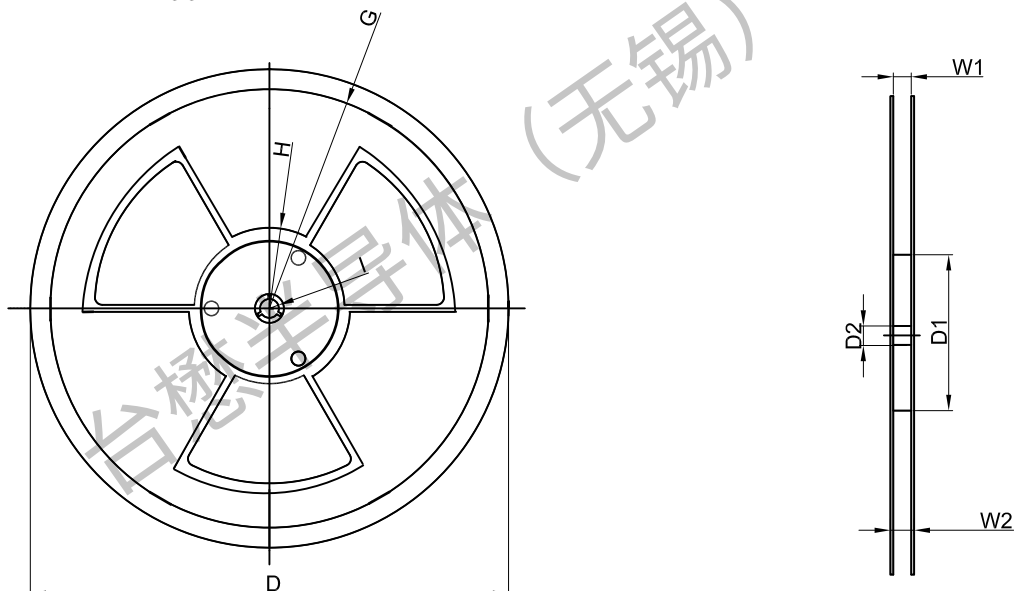
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
PDFN3×3-8L	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

PDFN3×3-8L Tape Leader and Trailer



PDFN3×3-8L Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13"Dia	Ø330.00	100.00	13.00	R135.00	R55.00	R6.50	12.00	14.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
5,000 pcs	13 inch	10,000 pcs	370×355×52	50,000 pcs	400×360×368	

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Revision history:

Date	Rev	Description	Page
2023.05.14	23.05	Original	